MUR520 THRU MUR560

5.0 AMP SURFACE MOUNT SUPER FAST RECTIFIERS

VOLTAGE RANGE
200 to 600 Volts
CURRENT
5.0 Ampere

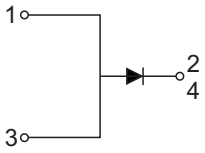
FEATURES

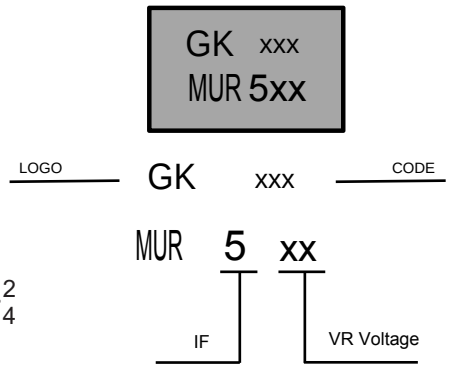
* Ideal for surface mount applications
* Easy pick and place
* Built-in strain relief
* Fast switching speed

MECHANICAL DATA

* Case: Molded plastic
* Epoxy: UL 94V-0 rate flame retardant
* Lead: Lead solderable per MIL-STD-202, method 208 guranteed
* Polarity: As Marked
* Mounting position: Any
* Weight: 2.24 grams







TO-252

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MUR520	MUR540	MUR560	UNITS
Maximum Recurrent Peak Reverse Voltage	200	400	600	V
Maximum RMS Voltage	140	280	420	V
Maximum DC Blocking Voltage	200	400	600	V
Maximum Average Forward Rectified Current		5.0		A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)		120		A
Maximum Instantaneous Forward Voltage at 5.0A	1.0	1.25	1.7	V
Maximum DC Reverse Current Ta=25℃		5.0		μA
at Rated DC Blocking Voltage Ta=100℃		150		μA
Maximum Reverse Recovery Time (Note 1)		35		nS
Typical Junction Capacitance (Note 2)		50		pF
Operating and Storage Temperature Range T_J, T_{STG}		-65 — +150		℃

NOTES:

1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

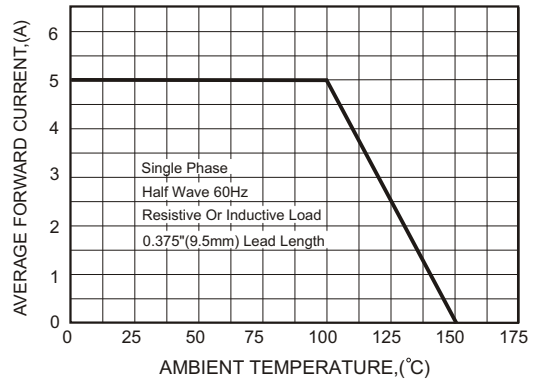


FIG.2-TYPICAL FORWARD CHARACTERISTICS

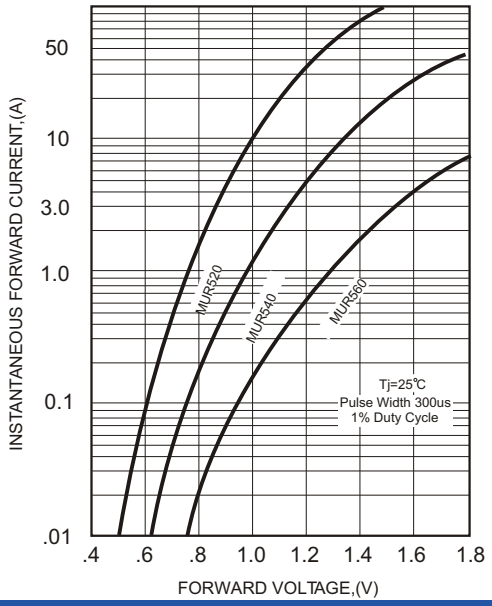
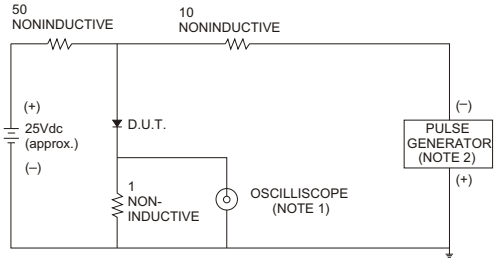


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

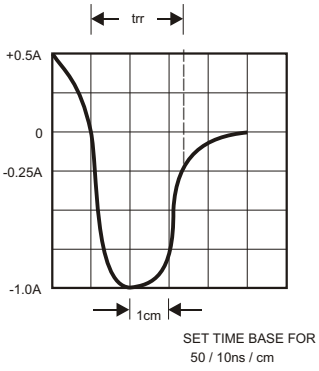


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

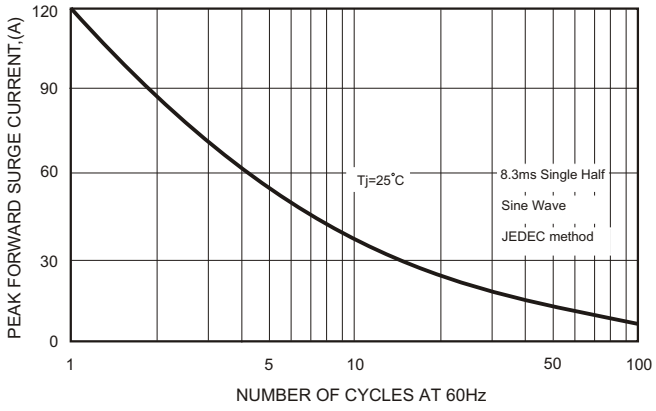


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

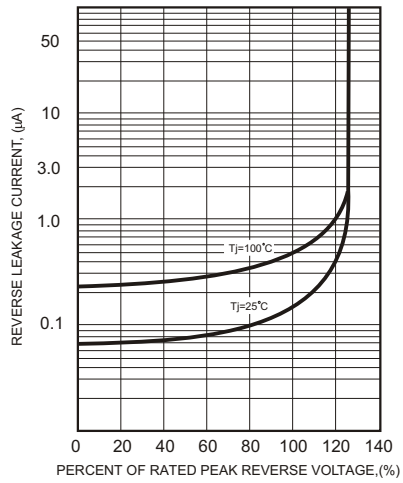
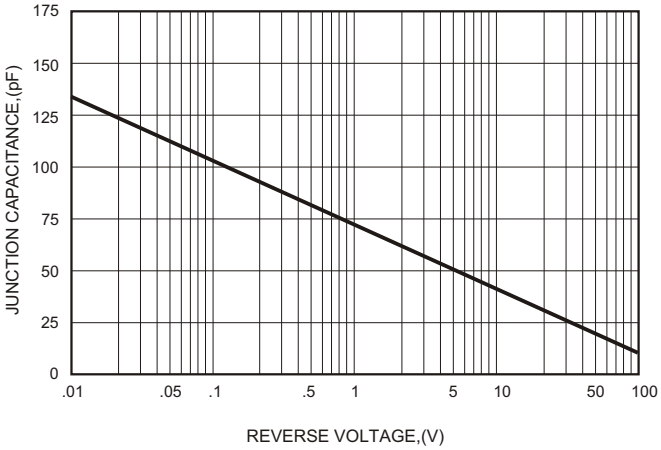


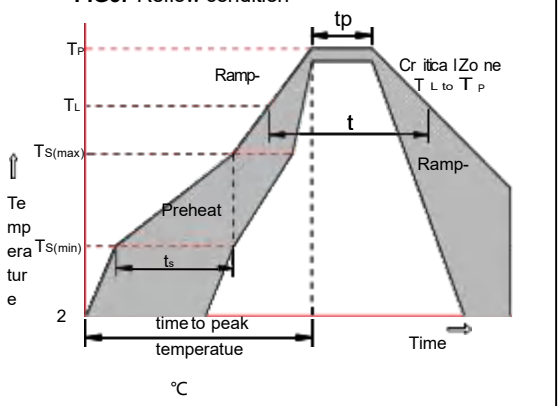
FIG.6-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

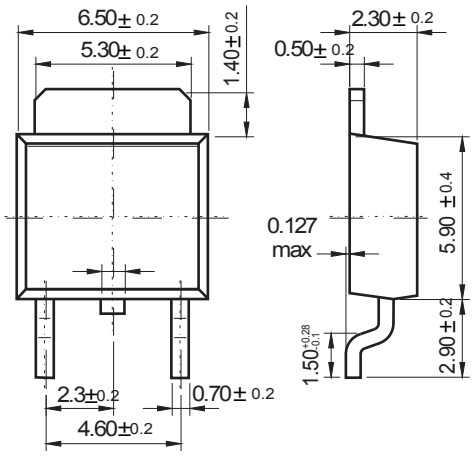
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition

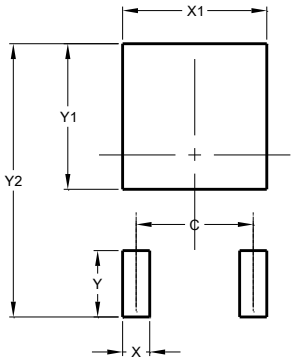


Package Dimensions & Suggested Pad Layout

TO-252



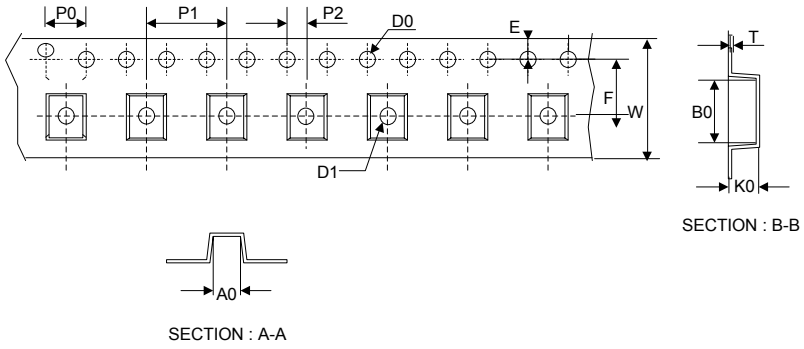
Dimensions in inches and (millimeters)



Dimensions	Value (in mm)
C	4.55
X	1.50
X1	5.80
Y	2.70
Y1	6.00
Y2	10.90

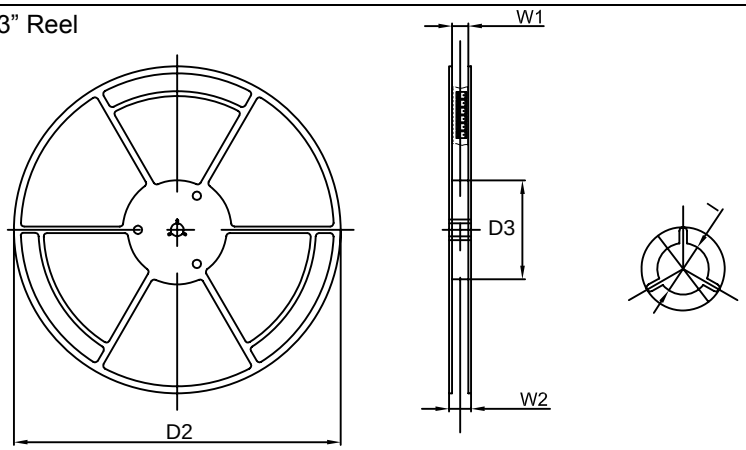
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.55±0.15
D1	1.55±0.20
E	1.75±0.20
F	7.50±0.20
W	16.00±0.20
A0	7.10±0.20
B0	10.50±0.20
K0	2.70±0.20
T	0.30±0.10

13” Reel



D2	330.0±5.0
D3	100.0±4.0
W1	20.0±5.0
W2	25.0±5.0
I	13.0±2.0

Quantity: 2500PCS